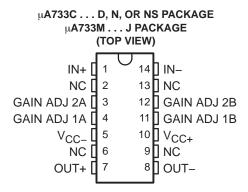
- 200-MHz Bandwidth
- 250-kΩ Input Resistance

- Selectable Nominal Amplification of 10, 100, or 400
- No Frequency Compensation Required

 $\mu$ A733M . . . U PACKAGE



(TOP VIEW)

IN+

IN+

1 10 IN
GAIN ADJ 2A

2 9 GAIN ADJ 2B

GAIN ADJ 1A

3 8 GAIN ADJ 1B

VCC
OUT+

5 6 OUT-

NC - No internal connection

### description/ordering information

The μA733 is a monolithic two-stage video amplifier with differential inputs and differential outputs. Internal series-shunt feedback provides wide bandwidth, low phase distortion, and excellent gain stability. Emitter-follower outputs enable the device to drive capacitive loads, and all stages are current-source biased to obtain high common-mode and supply-voltage rejection ratios.

Fixed differential amplification of 10 V/V, 100 V/V, or 400 V/V may be selected without external components, or amplification may be adjusted from 10 V/V to 400 V/V by the use of a single external resistor connected between 1A and 1B. No external frequency-compensating components are required for any gain option.

The device is particularly useful in magnetic-tape or disc-file systems using phase or NRZ encoding and in high-speed thin-film or plated-wire memories. Other applications include general-purpose video and pulse amplifiers where wide bandwidth, low phase shift, and excellent gain stability are required.

The  $\mu$ A733C is characterized for operation from 0°C to 70°C; the  $\mu$ A733M is characterized for operation over the full military temperature range of –55°C to 125°C.

#### ORDERING INFORMATION

TA	PACKAGE	<u>:</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
0°C to 70°C	P-DIP (N)	Tube of 25	UA733CN	UA733CN		
	0010 (D)	Tube of 50	UA733CD	1147000		
	SOIC (D)	Reel of 2500	UA733CDR	UA733C		
	SOP (NS)	Reel of 2000	UA733CNSR	UA733		

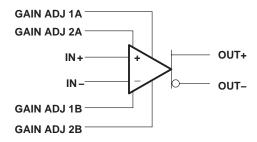
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



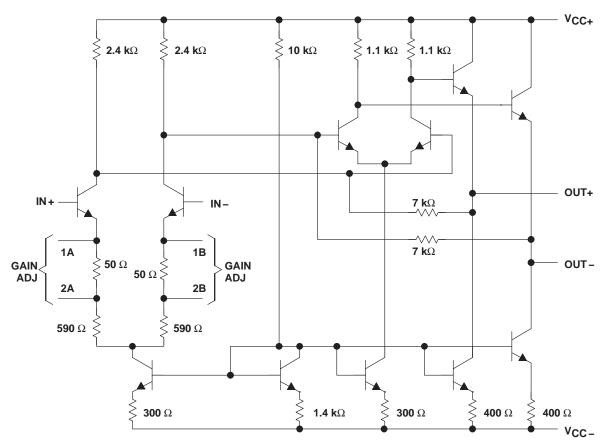
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### symbol



### schematic



Component values shown are nominal.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

	μ <b>Α733</b> C	μ <b>Α733</b> Μ	UNIT		
Supply voltage V <sub>CC+</sub> (see Note 1)	8	8	V		
Supply voltage V <sub>CC</sub> (see Note 1)		- 8	- 8	V	
Differential input voltage		± 5	± 5	V	
Common-mode input voltage	± 6	± 6	V		
Output current	10	10	mA		
Continuous total power dissipation	See Dissipation Rating Table				
	D package	86			
Package thermal impedance, θ <sub>JA</sub> (see Notes 2 and 3)	N package	80		°C/W	
	NS package	76			
Maximum junction temperature, TJ	150		°C		
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds		300	°C		
Storage temperature range, T <sub>Stg</sub>	- 65 to 150	- 65 to 150	°C		

<sup>†</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the recommended operating conditions section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltages, are with respect to the midpoint between V<sub>CC+</sub> and V<sub>CC-</sub>
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is PD =  $(T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### **DISSIPATION RATING TABLE**

	PACKAGE	$T_A \le 25^{\circ}C$ DERATING POWER RATING FACTOR		DERATE ABOVE T <sub>A</sub>	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING	
Γ	J (μΑ733M)	500 mW	11.0 mW/°C	104°C	500 mW	269 mW	



electrical characteristics,  $V_{CC\pm}$  =  $\pm 6$  V,  $T_A$  = 25°C

				GAIN	μ <b>Α733C</b>			μ <b>Α733Μ</b>			
PA	RAMETER	FIGURE	TEST CONDITIONS	OPTION†	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	Large-signal			1	250	400	600	300	400	500	
$A_{VD}$	differential voltage	1	V <sub>OD</sub> = 1 V	2	80	100	120	90	100	110	V/V
	amplification			3	8	10	12	9	10	11	
				1		50			50		
BW	Bandwidth	2	$R_S = 50 \Omega$	2		90			90		MHz
				3		200			200		
IIO	Input offset current			Any		0.4	5		0.4	3	μΑ
I <sub>IB</sub>	Input bias current			Any		9	30		9	20	μΑ
VICR	Common-mode input voltage range	1		Any	±1			±1			V
Voc	Common-mode output voltage	1		Any	2.4	2.9	3.4	2.4	2.9	3.4	V
.,	Output offset	1		1		0.6	1.5		0.6	1.5	.,
V <sub>00</sub>	OO voltage			2 & 3		0.35	1.5		0.35	1	V
VOPP	Maximum peak- to-peak output voltage swing	1		Any	3	4.7		3	4.7		V
	Input resistance	3	V <sub>OD</sub> ≤ 1 V	1		4			4		
rį				2	10	24		20	24		kΩ
				3		250			250		
r <sub>O</sub>	Output resistance					20			20		Ω
Ci	Input capacitance	3	$V_{OD} \le 1 \text{ V}$	2		2			2		pF
CMDD	Common-mode		$V_{IC} = \pm 1 \text{ V},$ f \leq 100 kHz	2	60	86		60	86		dB
CMRR	rejection ration	4	$V_{IC} = \pm 1 \text{ V},$ f = 5 MHz	2		70			70		ФВ
kSVR	Supply voltage rejection ratio (ΔV <sub>CC</sub> /(ΔV <sub>IO</sub> )	1	$\Delta V_{CC\pm} = \pm 0.5 \text{ V}$	2	50	70		50	70		dB
V <sub>n</sub>	Broadband equivalent input noise voltage	5	BW = 1 kHz to 10 MHz	Any		12			12		μV
	Propagation delay time		$R_S = 50 \Omega,$ Output voltage $step = 1 V$	1		7.5			7.5		
<sup>t</sup> pd		2		2		6.0	10		6.0	10	ns
				3		3.6			3.6		
	Rise time	2	$R_S = 50 \Omega$ ,	1		10.5			10.5		
t <sub>r</sub>				2		4.5	12		4.5	10	ns
				3		2.5			2.5		
I <sub>sink(max)</sub>	Maximum output sink current			Any	2.5	3.6		2.5	3.6		mA
Icc	Supply current		No load, No signal	Any		16	24		16	24	mA

<sup>†</sup>The gain option is selected as follows:

Gain Option 3: All four gain-adjust pins are open.



Gain Option 1: Gain-adjust pin 1A is connected to pin 1B, and pins 2A and 2B are open.

Gain Option 2: Gain-adjust pin 1A and pin 1B are open, pin 2A is connected to pin 2B.

# electrical characteristics, V<sub>CC $\pm$ </sub> = $\pm 6$ V, T<sub>A</sub> = 0°C to 70°C for $\mu$ A733C, – 55°C to 125°C for $\mu$ A733M

PARAMETER		FIGURE TEST COMPITIONS		GAIN	μ <b>Α733C</b>		μ <b>Α733Μ</b>		UNIT
		FIGURE	TEST CONDITIONS	OPTION†	MIN	MAX	MIN	MAX	UNIT
				1	250	600	200	600	
AVD	Large-signal differential voltage amplification	1	V <sub>OD</sub> = 1 V	2	80	120	80	120	V/V
	voltage amplification			3	8	12	8	12	
Io	Input offset current			Any		6		5	μΑ
I <sub>IB</sub>	Input bias current			Any		40		40	μΑ
VICR	Common-mode input voltage range	1		Any	±1		±1		V
.,	Output offset voltage	1		1		1.5		1.5	V
V00				2 & 3		1.5		1.2	V
V <sub>OPP</sub>	Maximum peak-to-peak output voltage swing	1		Any	2.8		2.5		V
rį	Input resistance	3	V <sub>OD</sub> ≤ 1 V	2	8		8		kΩ
CMRR	Common-mode rejection ratio	4	V <sub>IC</sub> = +1 V, f ≤ 100 kHz	2	50		50		dB
ksvr	Supply voltage rejection ratio (ΔV <sub>CC</sub> /(ΔV <sub>IO</sub> )	1	$\Delta V_{CC\pm} = \pm 0.5 \text{ V}$	2	50		50		dB
I <sub>sink(max)</sub>	Maximum output sink current			Any	2.5		2.2		mA
Icc	Supply current		No load, No signal	Any		27		27	mA

<sup>†</sup>The gain option is selected as follows:

Gain Option 1: Gain-adjust pin 1A is connected to pin 1B, and pins 2A and 2B are open.

Gain Option 2: Gain-adjust pin 1A and pin 1B are open, pin 2A is connected to pin 2B.

Gain Option 3: All four gain-adjust pins are open.

### PARAMETER MEASUREMENT INFORMATION

### test circuits

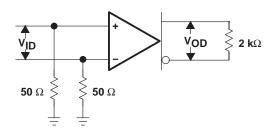


Figure 1

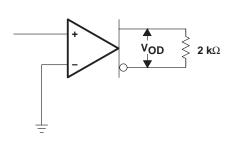


Figure 3

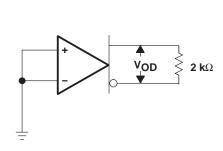


Figure 5

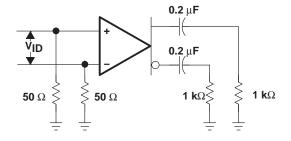


Figure 2

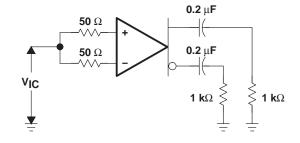
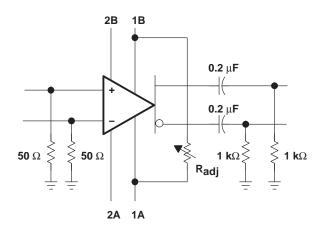


Figure 4



**VOLTAGE AMPLIFICATION ADJUSTMENT** 

Figure 6

### **TYPICAL CHARACTERISTICS**

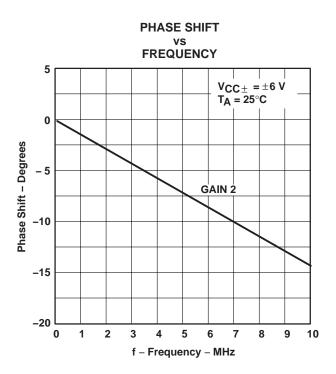
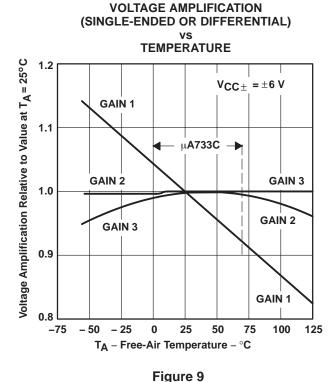
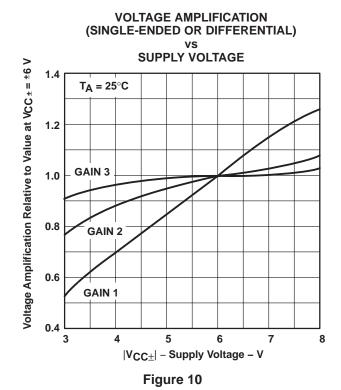


Figure 7



**PHASE SHIFT** vs **FREQUENCY** 50  $V_{CC\pm} = \pm 6 V$ 0 T<sub>A</sub> = 25°C - 50 GAIN 2 -100Phase Shift - Degrees -150-200 -250-300 -350-400 -450 40 4 10 100 400 f - Frequency - MHz

Figure 8



### TYPICAL CHARACTERISTICS

# DIFFERENTIAL VOLTAGE AMPLIFICATION vs RESISTANCE BETWEEN G1A AND G1B

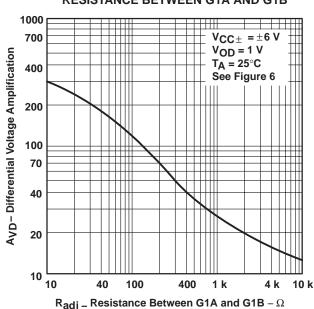


Figure 11

# SUPPLY CURRENT

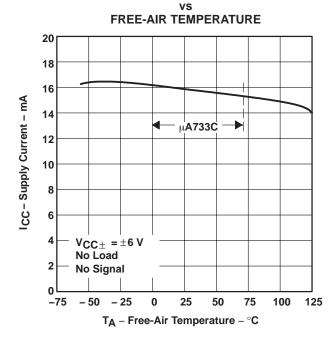


Figure 13

# SINGLE-ENDED VOLTAGE AMPLIFICATION vs

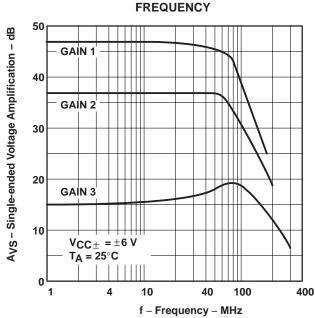


Figure 12

## SUPPLY CURRENT vs SUPPLY VOLTAGE

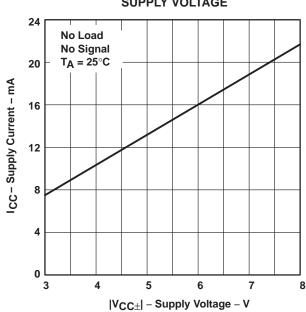


Figure 14

### **TYPICAL CHARACTERISTICS**

# MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs

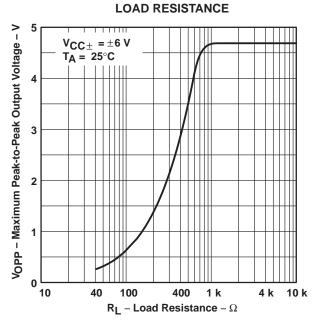


Figure 15

# MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs

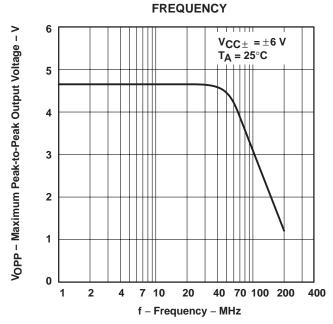


Figure 17

# MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE VS SUPPLY VOLTAGE

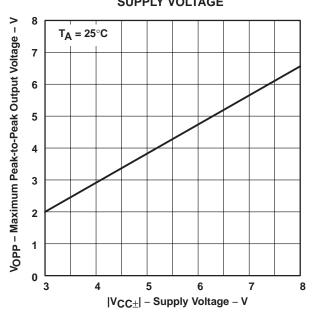
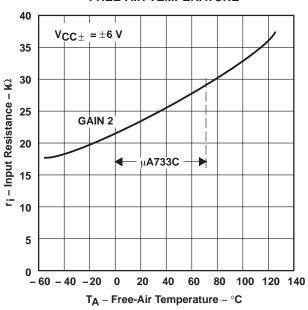


Figure 16

# INPUT RESISTANCE vs FREE-AIR TEMPERATURE



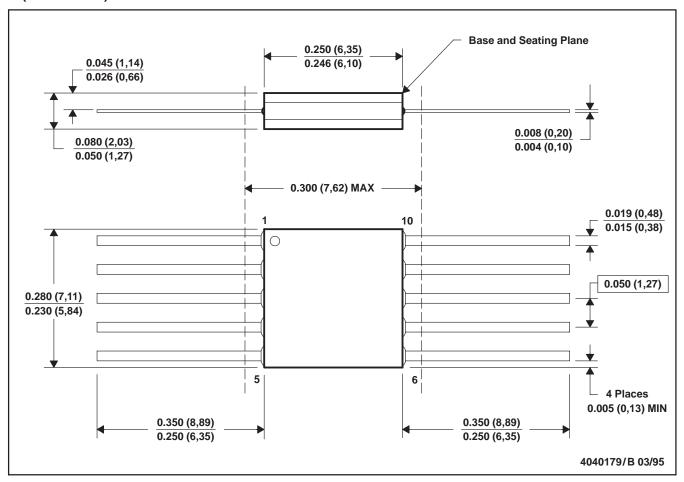
### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### U (S-GDFP-F10)

### **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

### FK (S-CQCC-N\*\*)

### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

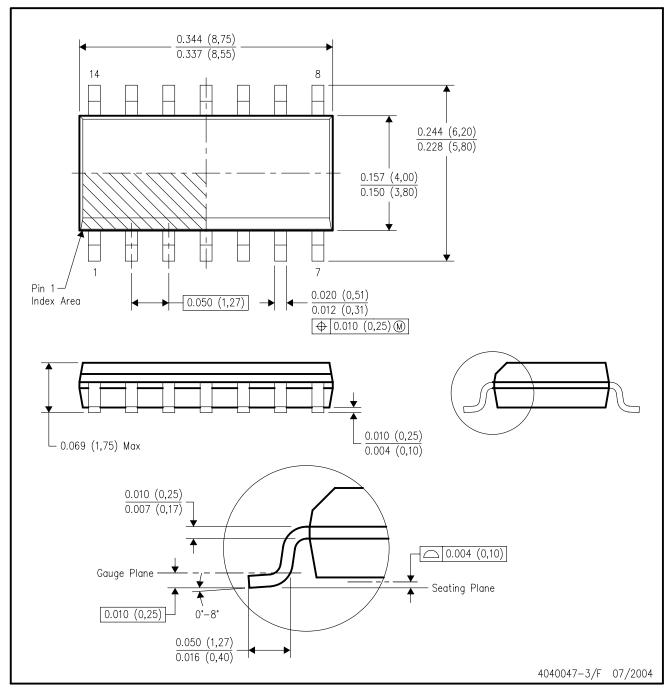


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDSO-G14)

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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